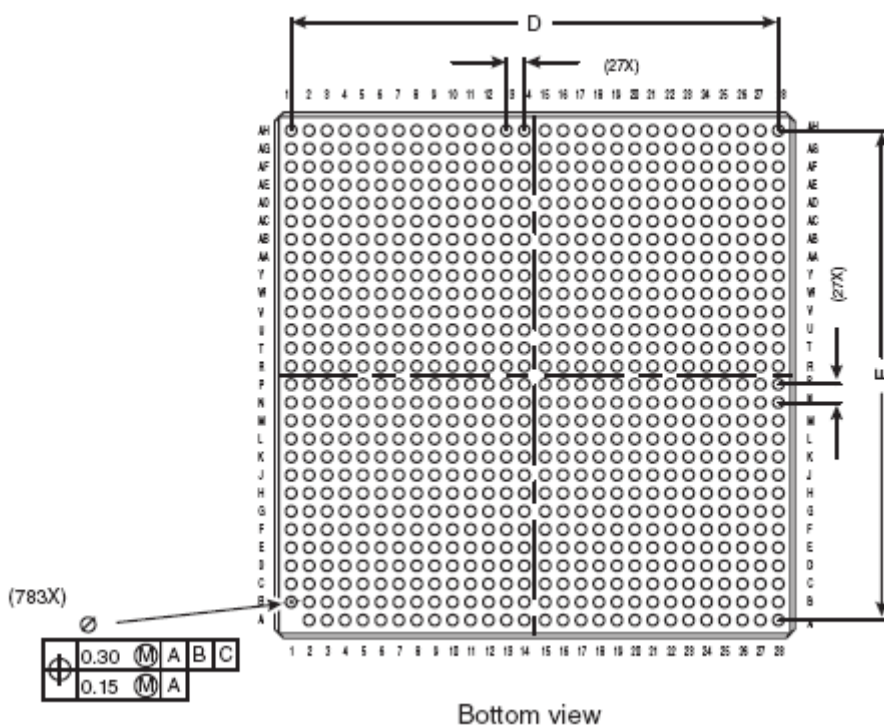
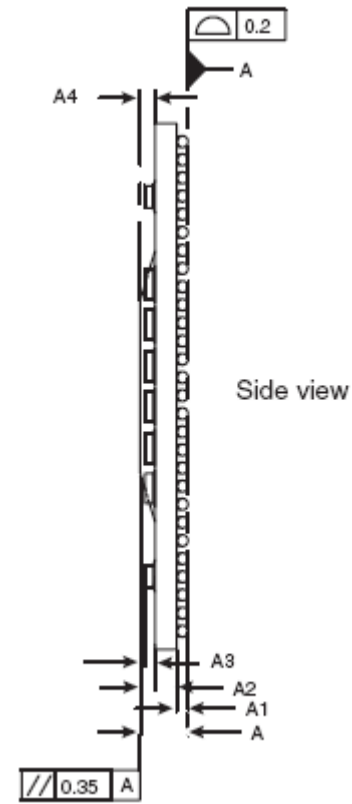
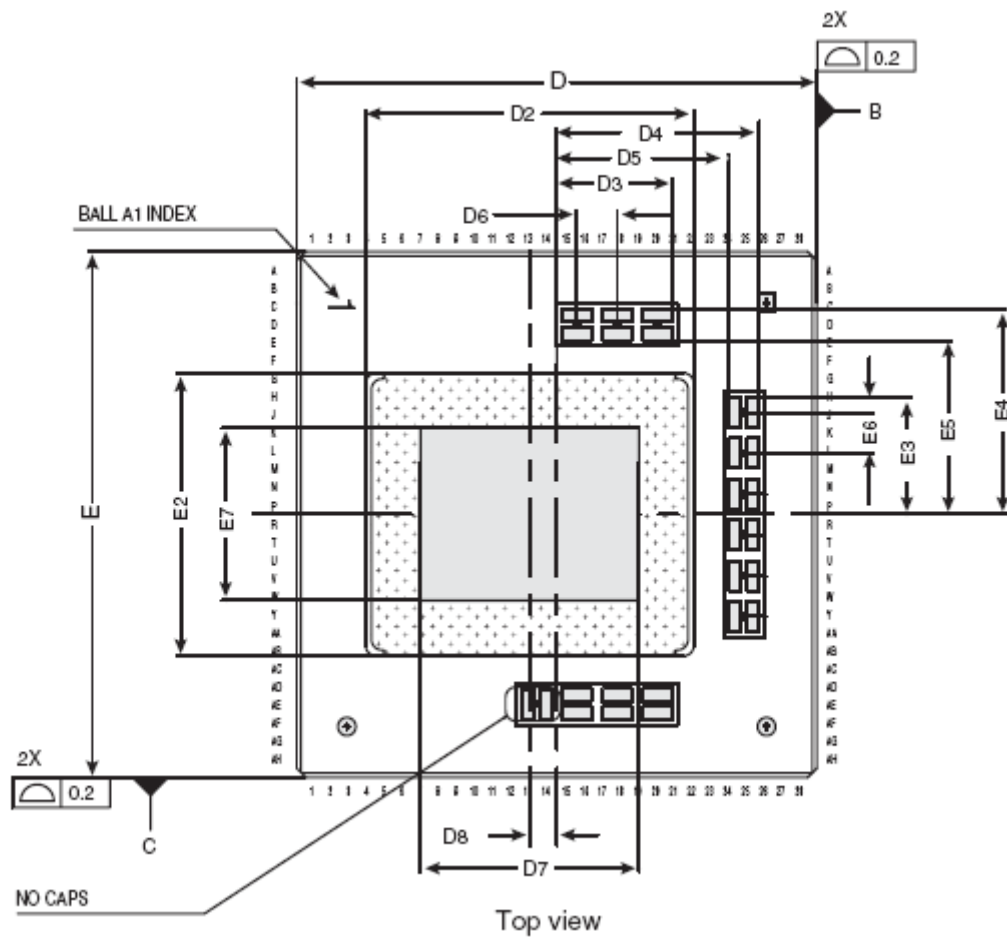


Package Mechanical Data

Package Parameters for the PC8540 HiTCE

The package parameters are as provided in the following list. The package type is 29 mm x 29 mm, 783 flip chip ball grid array (HiTCE).

Die size	12.2 mm x 9.5 mm
Package outline	29 mm x 29 mm
Interconnects	783
Pitch	1 mm
Minimum module height	2.36 mm
Maximum module height	2.86 mm
Solder Balls	90 Sn/10 Pb
Ball diameter (typical)	0.6 mm



Parameter	Min	Max
A	2.36	2.86
A1	0.53	0.74
A2	0.99	1.21
A3	-	0.60
A4	0.82	0.90
b	0.55	0.72
D	28.70	29.20
D1	27.00 BSC	
D2	-	18.30
D3	6.45 REF	
D4	11.30 REF	
D5	9.60 REF	
D6	2.25 REF	
D7	12.10	12.30
D8	1.50 REF	
e	1.00 BSC	
E	28.70	29.20
E1	27.00 BSC	
E2	-	15.60
E3	6.45 REF	
E4	11.30 REF	
E5	9.60 REF	
E6	2.25 REF	
E7	9.40	9.60